

IN THE CLAIMS:

Please AMEND the claims as follows:

Claims 1-7 are Withdrawn.

8. (Currently Amended) A method for fabricating a laminate circuit structure assembly which comprises: providing at least two modularized circuitized voltage plane subassemblies wherein each of the subassemblies comprise at least two signal planes having an external and internal surface disposed about an internal voltage plane; providing a dielectric material between the signal and voltage planes; and providing dielectric on each external surface of each signal plane; and providing a non-cured or partially cured curable dielectric composition between the subassemblies wherein the dielectric composition comprises, dielectric material that is of the same material as the dielectric material ~~dielectric~~ used in said subassemblies, aligning the subassemblies, and then laminating to cause bonding of the subassemblies.

9. (Previously Amended) The method of Claim 8, which further comprises: locating an interposer between the subassemblies wherein the interposer comprises dielectric layers disposed about an internal electrically conductive layer.

10. (Currently Amended) The method of Claim 9, wherein dielectric material of at least one of the surfaces that is to be bonded is from said dielectric composition.

11. (Previously Amended) The method of Claim 8, wherein vias are disposed within each subassembly for providing electrical communication between signal planes and electrical connection to another subassembly.

12. (Previously Amended) The method of Claim 11, wherein the vias through the signal planes are plated with a conductive metal.

13. (Previously Amended) The method of claim 11, wherein the vias are filled with conductive adhesive.

14. (Previously Amended) The method of Claim 9, wherein the internal electricity conductive layer of the interposer is copper.

15. (Previously Amended) The method of Claim 9, wherein the interposer is about 3 to about 10 mils thick.

16. (Previously Amended) The method of Claim 8, which comprises: providing top and bottom circuit layers on top and bottom external surfaces of the assembly.

17. (Previously Amended) The method of Claim 8, wherein the laminating is carried out at about 100 to about 200°C, for about 15 minutes to about 90 minutes, and at a pressure of about 100 to about 500 psi.
